



Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"] 1 FR4/G10 or equivalent high temp material; Non-clad



Pins: material- Brass Alloy 360 1/2 hard; finish- $0.25\mu m$ [10μ "] Au over $1.27\mu m$ [50μ "] Ni (min.).



Solder Balls: Sn63Pb37

Description: Giga-snaP BGA SMT Foot

125 position terminal pins (0.8mm centers, 13x13 array) to SMT solder balls (BGA type). Pin asignment 1:1.

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

